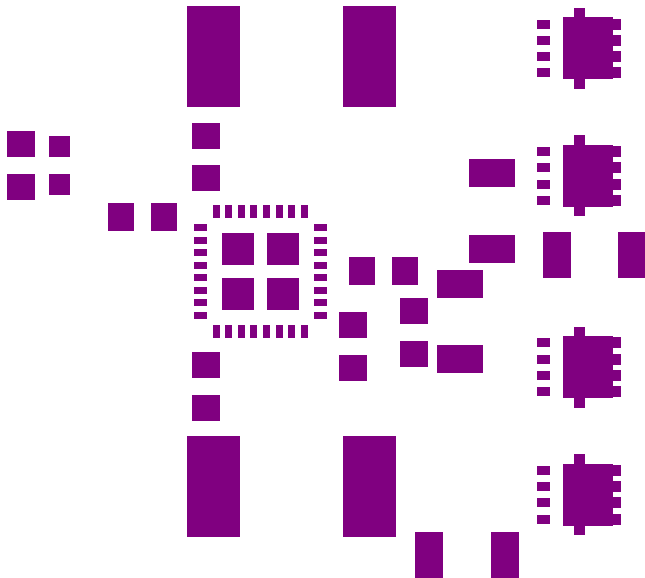
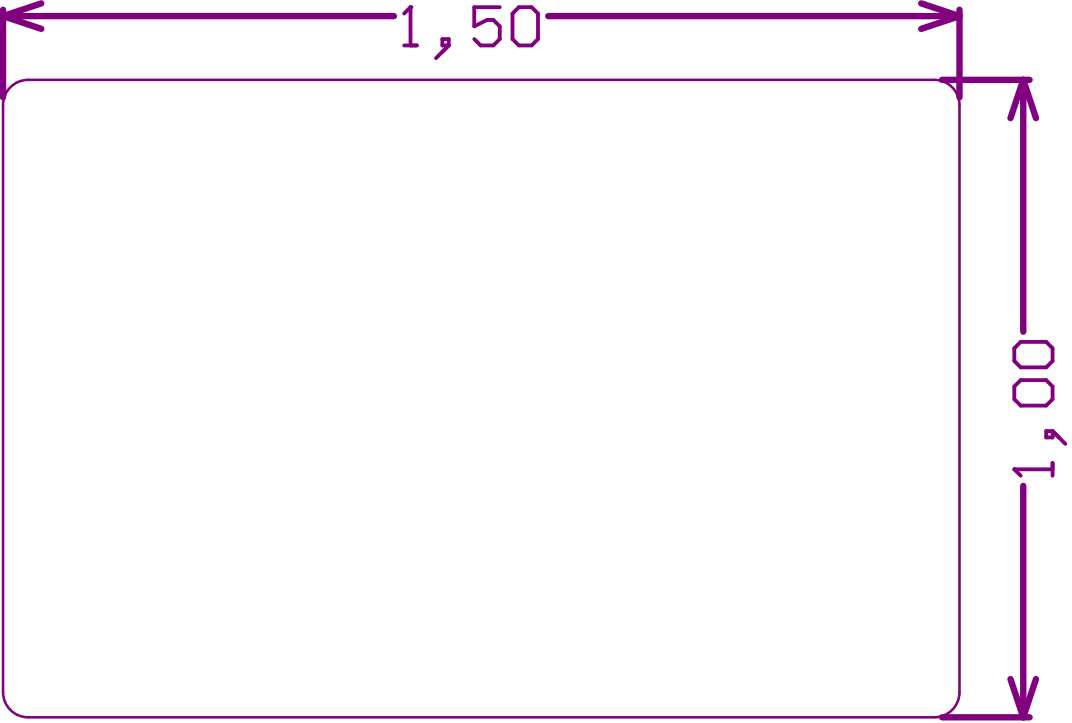
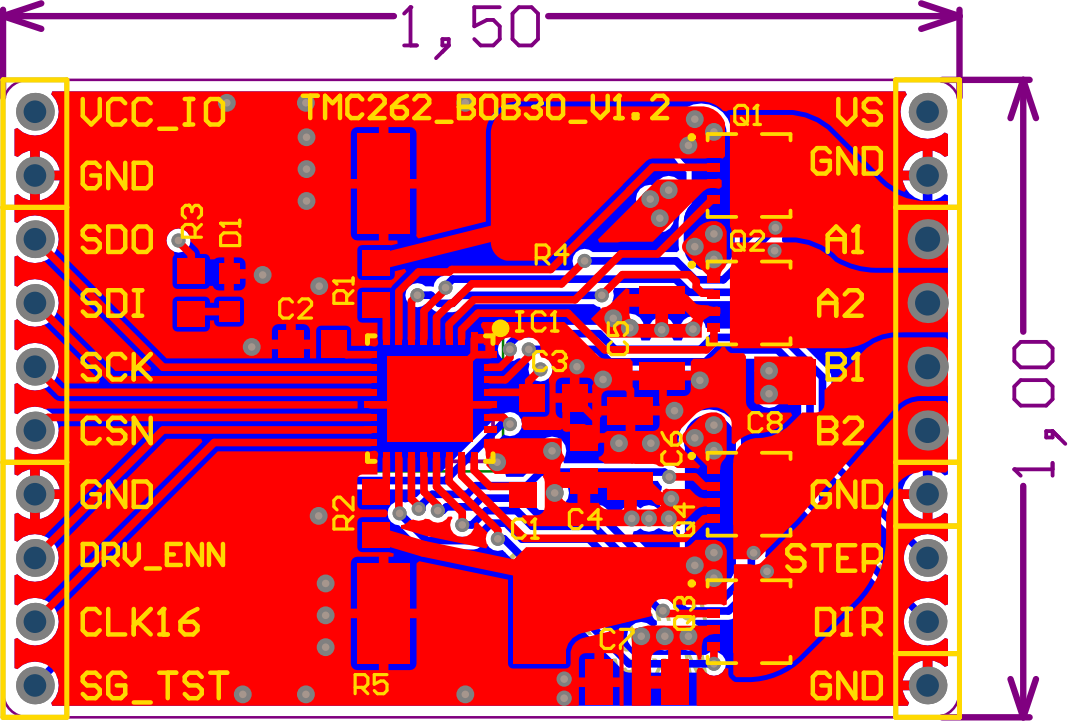
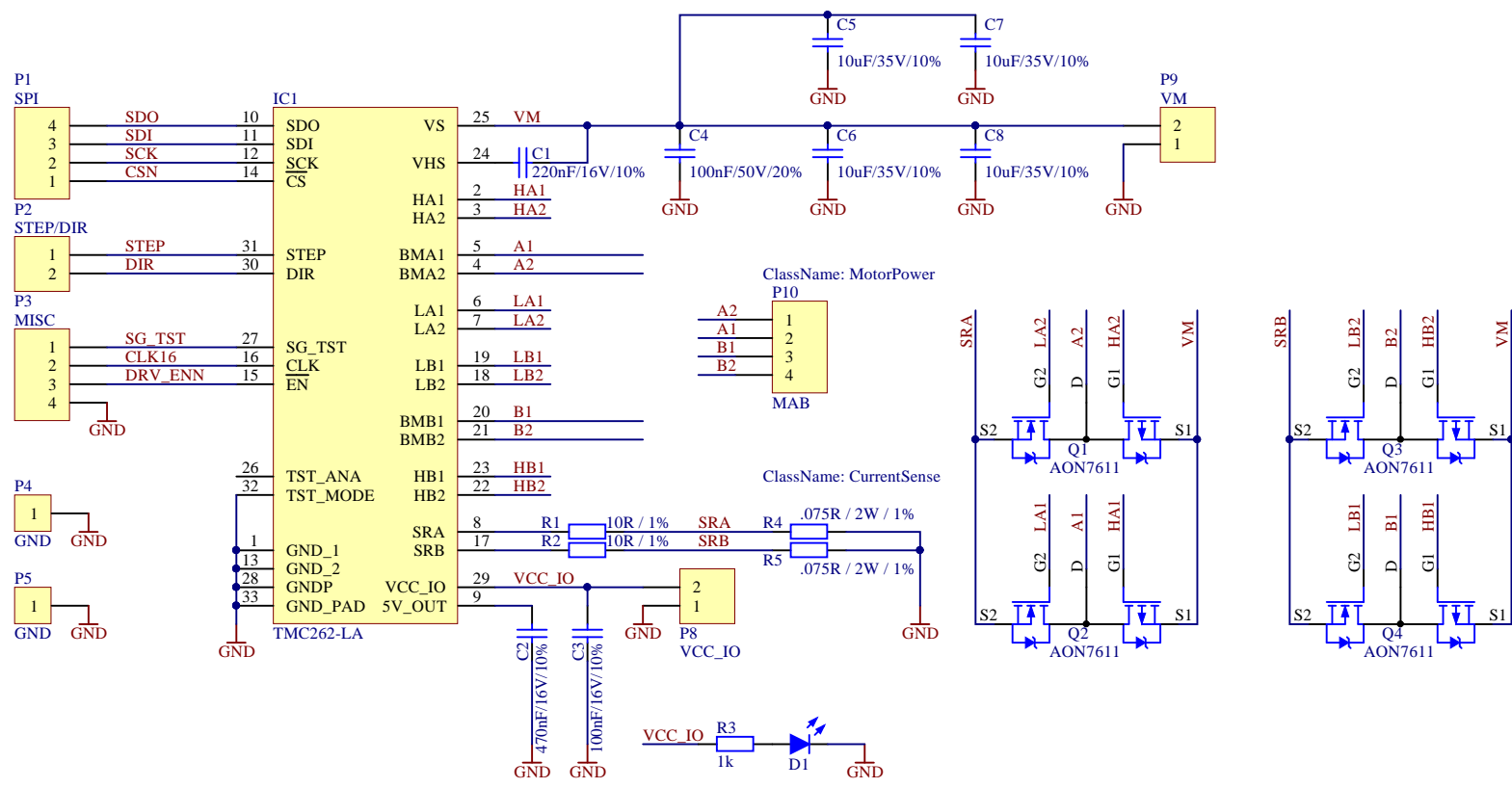


VS		VCC_IO
GND		GND
A1		SDO
A2		SDI
B1		SCK
B2		CSN
GND		GND
STEP	TMC262_BOB30_V1.2	DRV_ENN
DIR	IC name: TMC262-LA Supply range: VS = 9...30V Max. current: IRMS = 2.8A	CLK16
GND		SG_TST



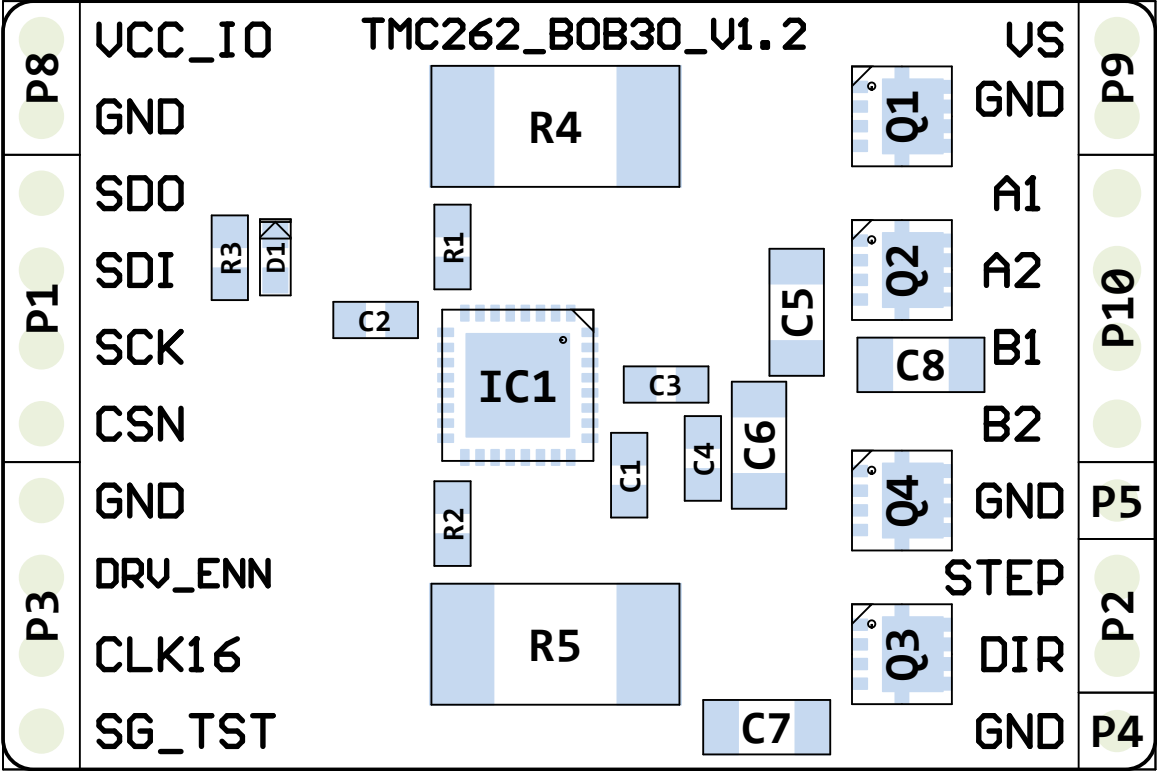




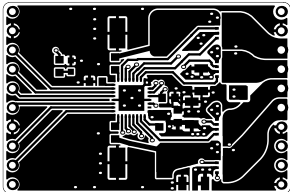


Title		
TMC262_BOB30		
Size	Number	Revision
A4		1.2
Date:	18.07.2017	Sheet of
File:	C:\Users\...\TMC262_BOB30_V1_2.SchDoc	Drawn By:

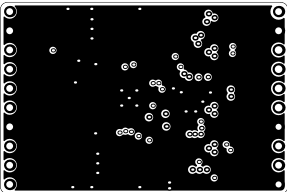
View from Top side (Scale 4:1)



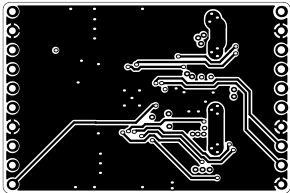
Top (Scale 1:1)



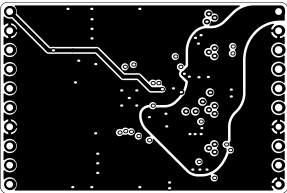
GND (Scale 1:1)



Bottom (Scale 1:1)



VM (Scale 1:1)



ChangeLog

V1.0 - Initial design

V1.1 - Redesign and Optimization after 1st Round

- + Added 2 additional 10uF ceramic caps.
- + Added bottom side labels (IC Name, Supply range, Max. current):
TMC262-LA, VS = 9...30V, IRMS = 2.8A
- + Changed left connector: pin 1 = VCCIO, pin 2 = GND
STEP and DIR had to be moved to the right connector.
- + Changed left and right side connectors to have same signals/pinning as TMC260/261/2660
- + Changed silkscreen text width from 5mil to 7mil.
- + Changed board name text height to 35mil.

V1.2 - Changed pin hole diameters from 0.9mm to 1mm for header P10 (MAB).

Title <i>TMC262_BOB30</i>			
Size A4	Number		Revision <i>1.2</i>
Date:	18.07.2017	Sheet of	
File:	C:\Users\...\ChangeLog.SchDoc	Drawn By:	

